

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	2,09mil	3.5	
1	Top Layer		2,76mil		
	Dielectric1	FR-4	9,13mil	4.8	
2	Mid-Layer 1		1,40mil		
	Dielectric2	FR-4	27,95mil	4.8	
3	Mid-Layer 2		1,40mil		
	Dielectric3	FR-4	12,60mil	4.8	
4	Bottom Layer		2,76mil		
	Bottom Solder	Solder Resist	0,21mil	3.5	
	Bottom Overlay				

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL
 MIN. CLEARANCE: 0.2 mm
 MIN. VIA PAD SIZE: 24 MIL
 MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
 PER IPC-D-275 CLASS 2 LEVEL C
 REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
 HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
 FR-408 FR-4 High Tg OTHER

THICKNESS: 62 MIL (1.6mm) +/-10% OTHER

TOLERANCE: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/-

BOW & TWIST: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/-

DRILLING:
 REFERENCE: AS SHOWN NC_DRILL FILES
 PTH COPPER THICKNESS: 20-30 um OTHER

BOARD FINISH:
 SILKSCREEN: TOP BOTTOM
 SILKSCREEN COLOR: WHITE OTHER
 SOLDER RESIST COLOR: GREEN OTHER
 MATTE SEMI-GLOSS

SURFACE FINISH: IMMERSION GOLD (ENIG) ENEPG
 IMM. TIN/SILVER OR EQUIV OTHER

ARRAY/PANEL: CUT AND TRIM PER M1 BOARD OUTLINE
 N.C. ROUTE V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:
 ANSI IPC-A-600F CLASS -> 1 2 3
 RoHS OTHER PER ORDER

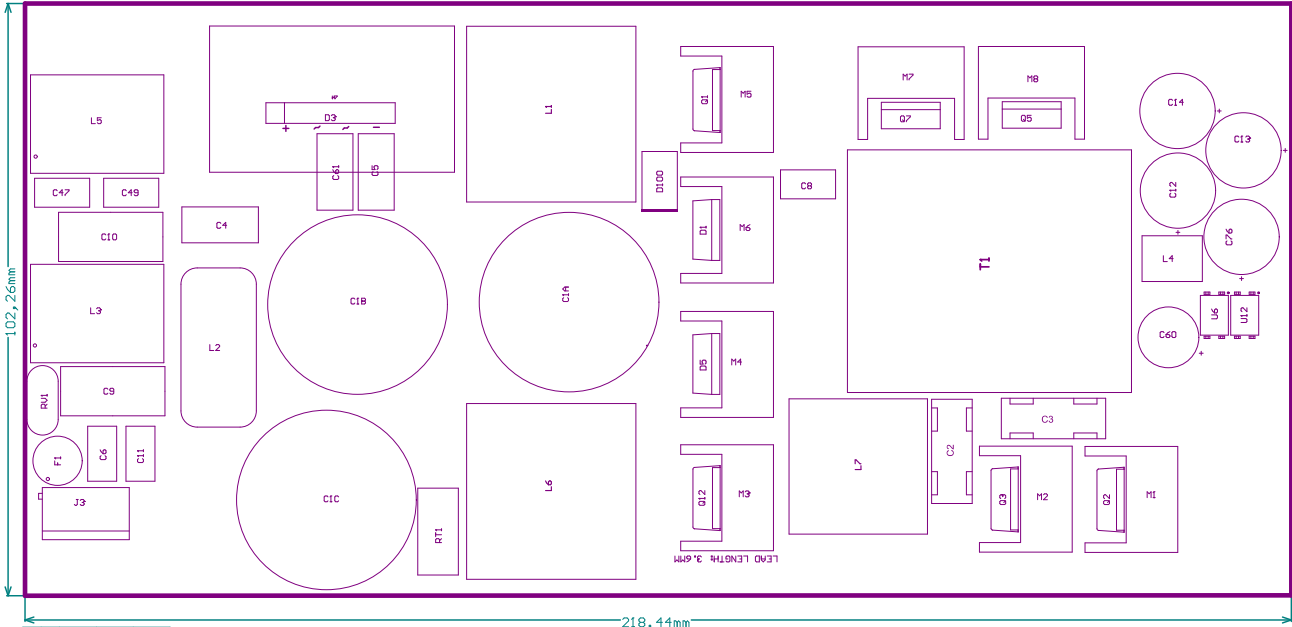
ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
 PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
 MICROSECTION: YES

BARE BOARD ELEC. TEST: NONE REQUIRED PER ORDER

XX MIL VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE
 XX MIL VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE
 OUTER XX MIL TRACES REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE
 LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE

24/05/2022 13:52:56



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: [No Variations]

The PMP31179 Rev_A board is built on PMP30763 Rev_D PCB

PCB NETWORK FROM BOARD TOP SIDE	BOARD #: PMP31179	REV: D	SUN REV: Not in version control
LAYER NAME = MEZBANKTOP	TID #:		
PLOT NAME = Top Layer Assembly Drawing	GENERATED : 24/05/2022 13:52:56	TEXAS INSTRUMENTS	

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TEXAS INSTRUMENTS

PROJECT TITLE:
400W, PFC + LLC for Avionics

DESIGNED FOR:
Public Release

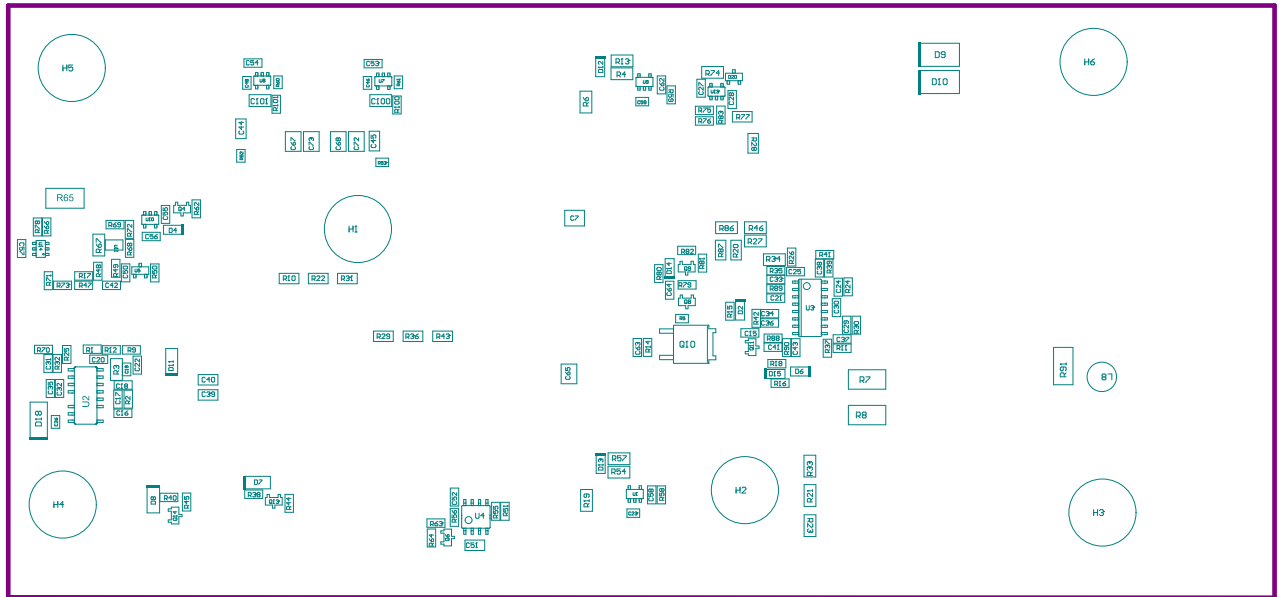
FILE NAME:
PMP31179_Rev_A_board.PcbDoc

ENGINEER:
R. Scibilia

LAYOUT BY:
PMP30763

SCALE: 0.77

ALTIM DESIGNER VERSION:
22.5.1.42



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PMP31179	REV: D	SUN REV: Not in version control
	TID #:	eniruo br6o8 IM	
PLOT NAME = Bottom Layer Assembly Drawing GENERATED : 24/05/2022 13:52:56			TEXAS INSTRUMENTS

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